US00D323173S

United States Patent [19]

Ishii et al.

[11] **Patent Number: Des. 323,173**

[45] **Date of Patent: ** Jan. 14, 1992**

[54] **INSTRUMENT FOR TRANSFERRING BOATS FOR THERMAL TREATMENT OF SEMICONDUCTOR WAFERS**

[75] Inventors: **Katsumi Ishii**, Fujino; **Mitsuo Katoh**, Sagamihara, both of Japan

[73] Assignee: **Tel Sagami Limited**, Kanagawa, Japan

[**] Term: **14 Years**

[21] Appl. No.: **301,996**

[22] Filed: **Jan. 25, 1989**

[30] **Foreign Application Priority Data**

Jul. 25, 1988 [JP] Japan 63-29831

[52] **U.S. Cl.** **D15/199**

[58] **Field of Search** D15/144, 199; 219/390, 219/411; 414/222, 225, 226, 433; 432/6, 33, 153, 239, 253, 258-261

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 210,208	2/1968	Frelin	D15/144 X
3,961,877	6/1976	Johnson	432/253
4,041,278	8/1977	Boah	432/259 X

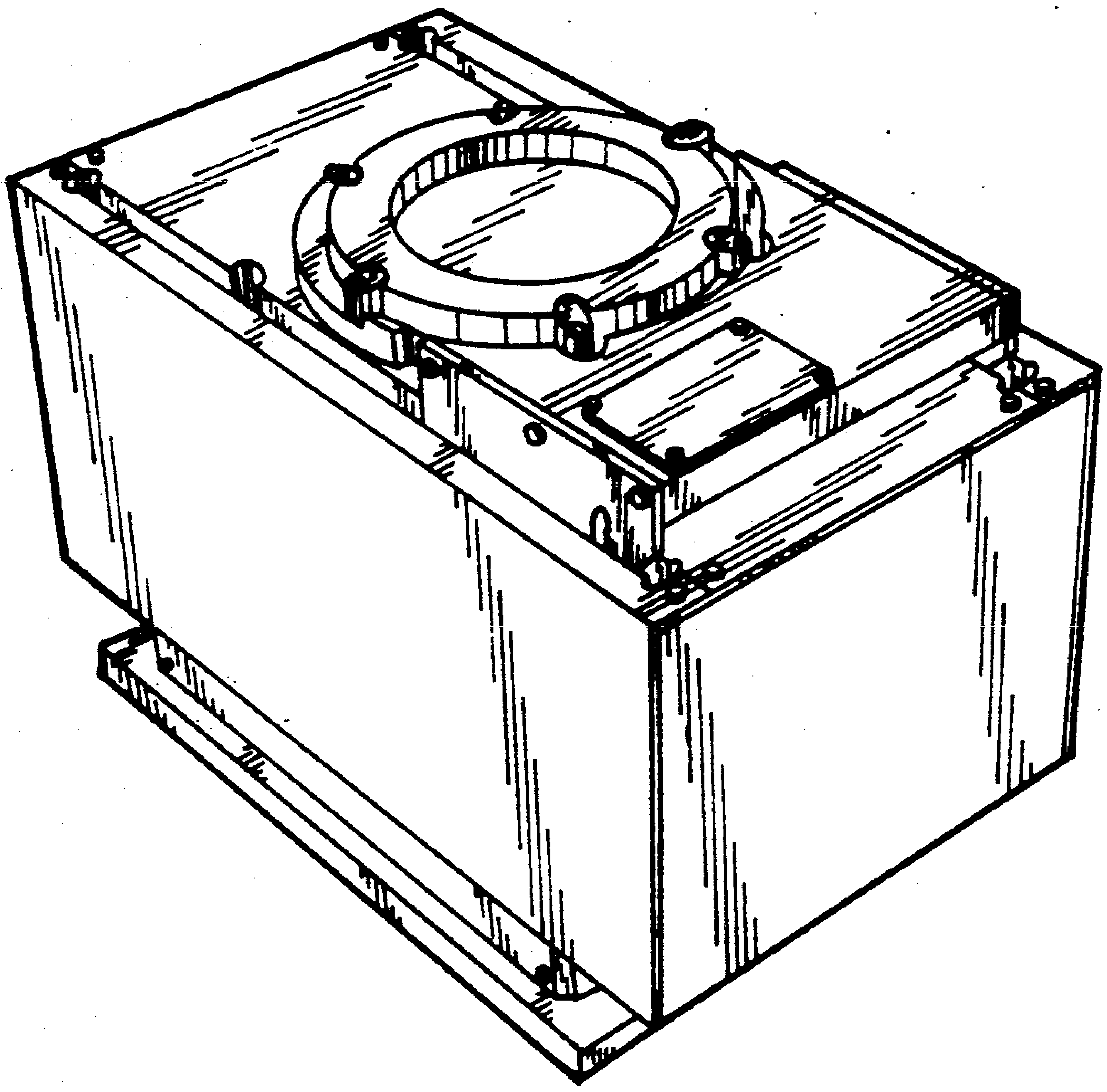
Primary Examiner—Bruce W. Dunkins
Assistant Examiner—Antoine D. Davis
Attorney, Agent, or Firm—Oblon, Spivak, McClelland, Maier & Neustadt

[57] **CLAIM**

The ornamental design for an instrument for transferring boats for thermal treatment of semiconductor wafers, as shown and described.

DESCRIPTION

FIG. 1 is a top, front and right side perspective view of an instrument for transferring boats for thermal treatment of semiconductor wafers showing our new design;
FIG. 2 is a left side elevational view;
FIG. 3 is a front elevational view, the rear elevational view being a mirror image;
FIG. 4 is a top plan view;
FIG. 5 is a bottom plan view; and
FIG. 6 is a right side elevational view thereof.



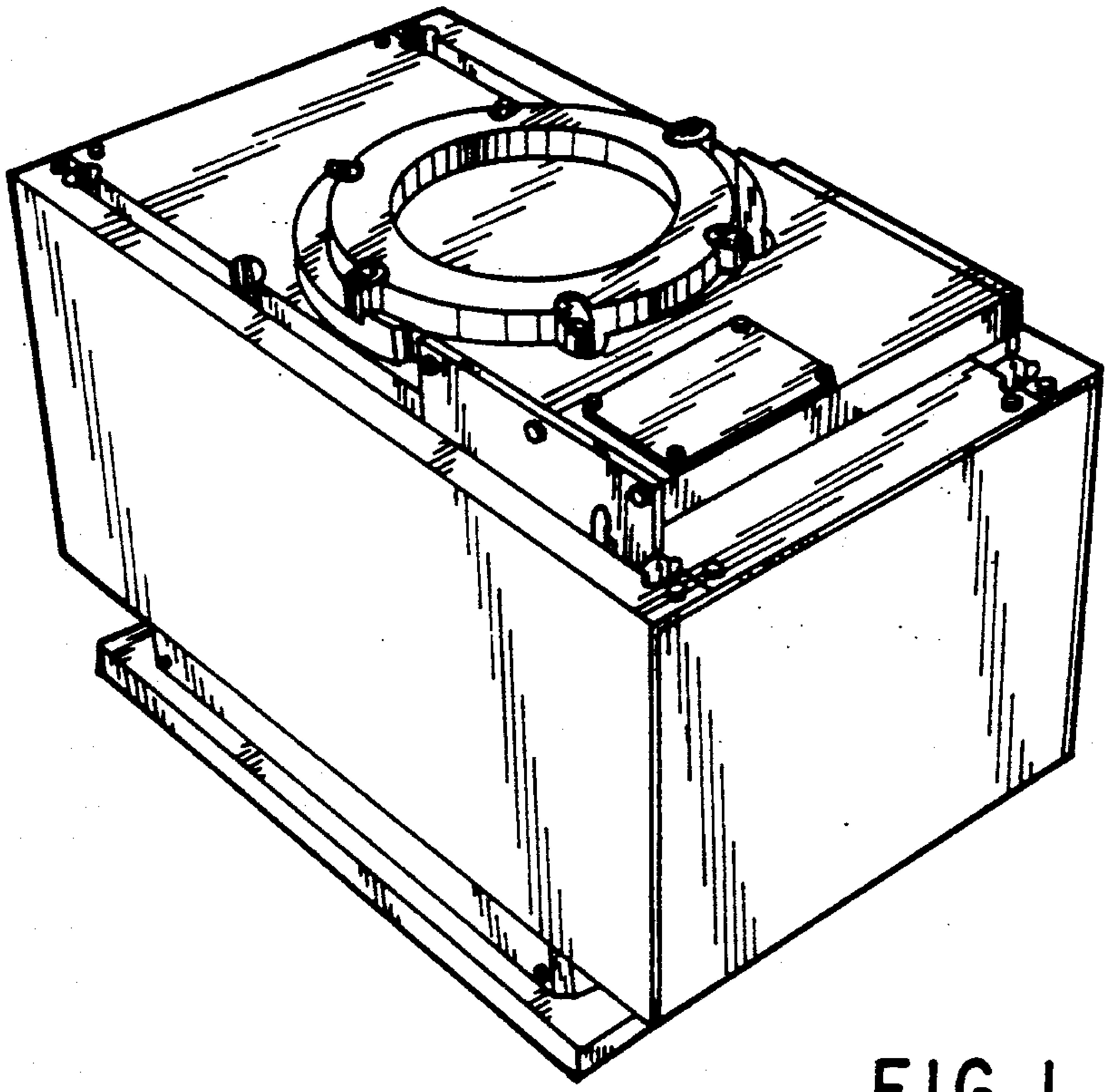


FIG.1

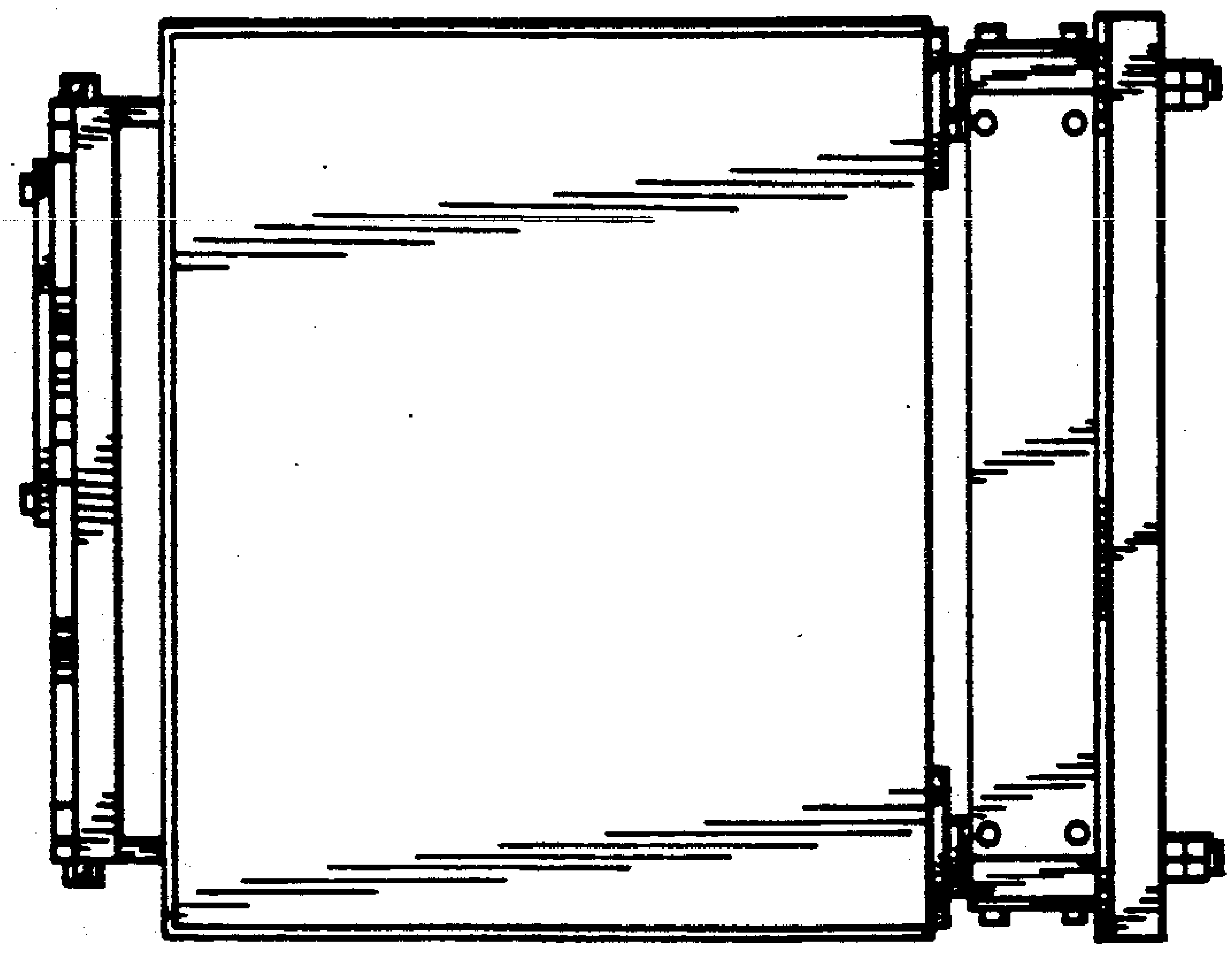


FIG. 2

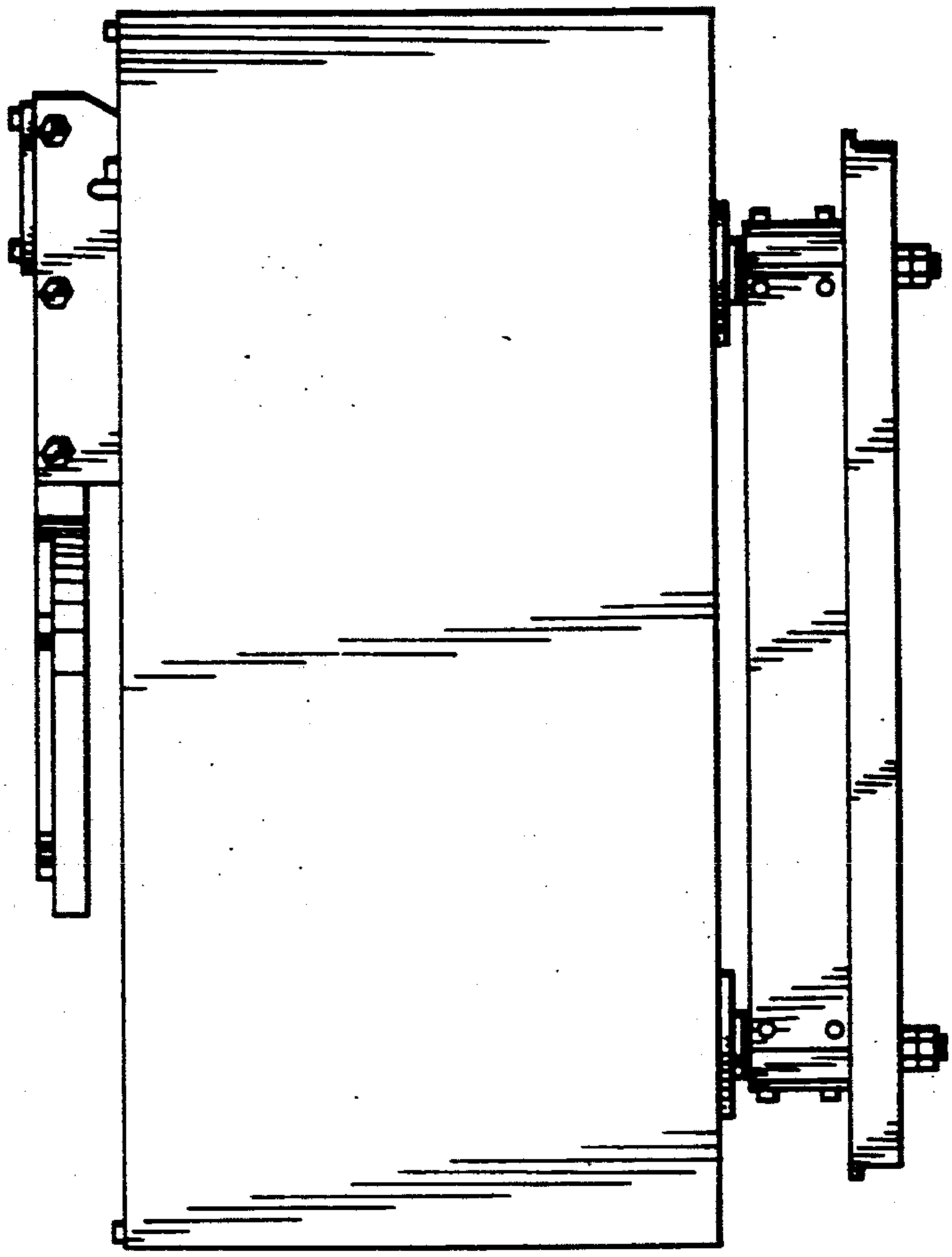


FIG. 3

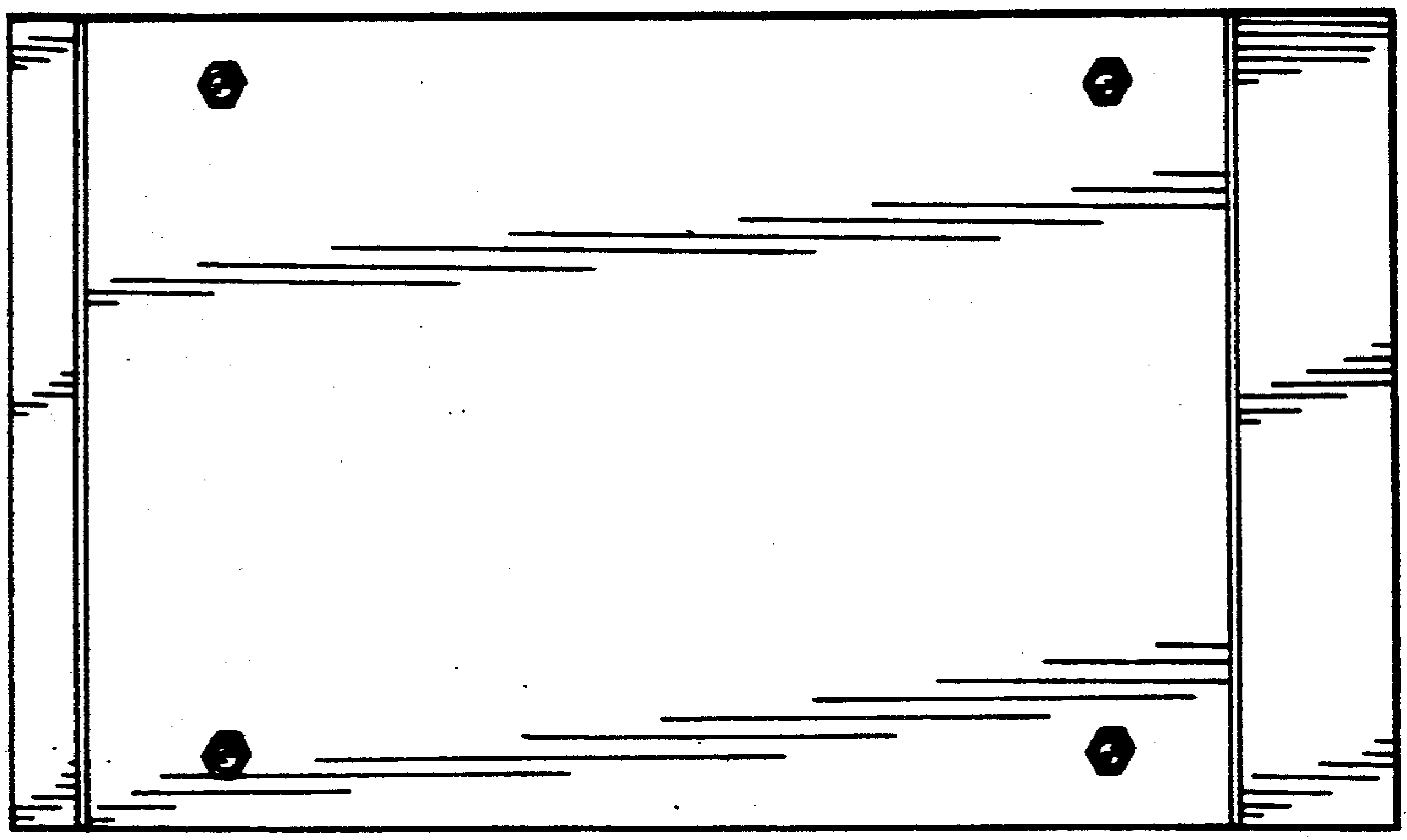


FIG. 5

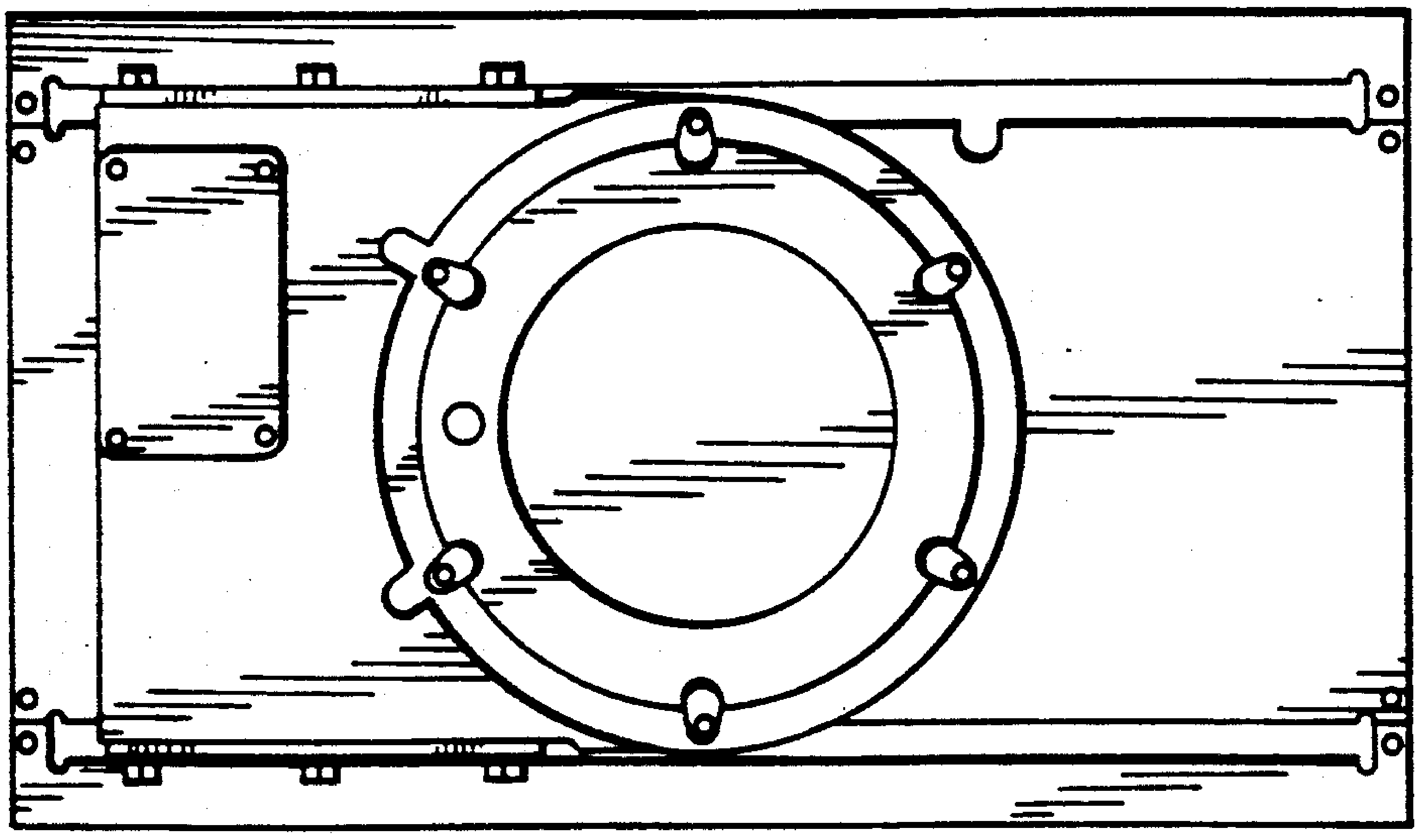


FIG. 4

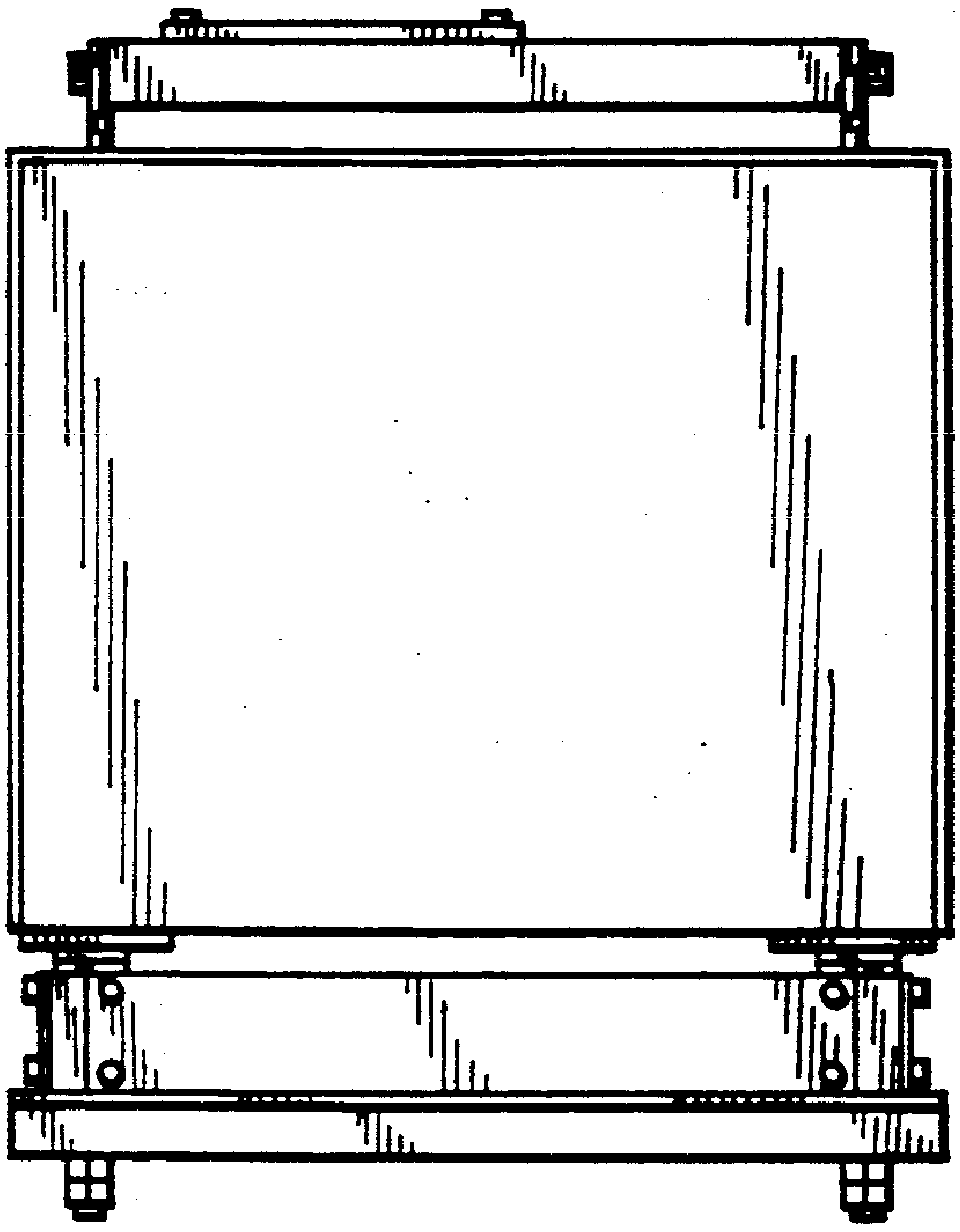


FIG.6